

# Handling Partial Correlations in Yield Prediction

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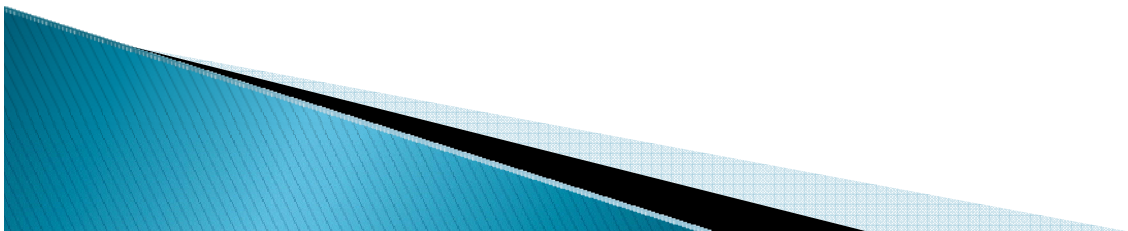
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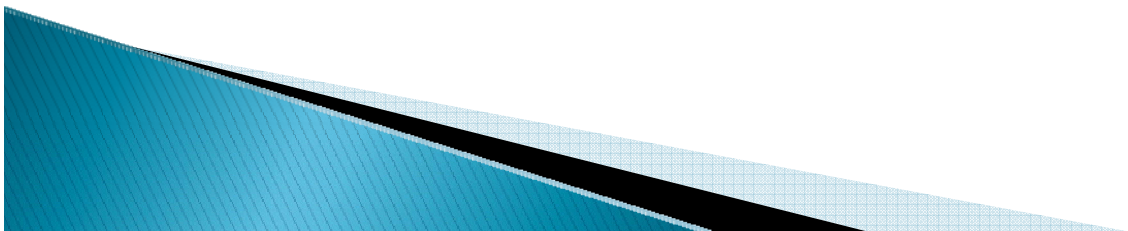
# Presentation Outline

- **What is Yield?**
- Difficulties in Yield Prediction
- Previous Research
- Proposed Research
- Simulation Results
- Conclusion



# What is Yield?

- ▶ Yield – Probability of any Manufacturing or Parametric spec satisfying its limits.
- ▶ Manufacturing Yield – for manufacturing specs.
- ▶ Parametric Yield – performance measures (timing, power etc.)
- ▶ Process variations affect yield prediction.
- ▶ Intra–die process variations no longer negligible.



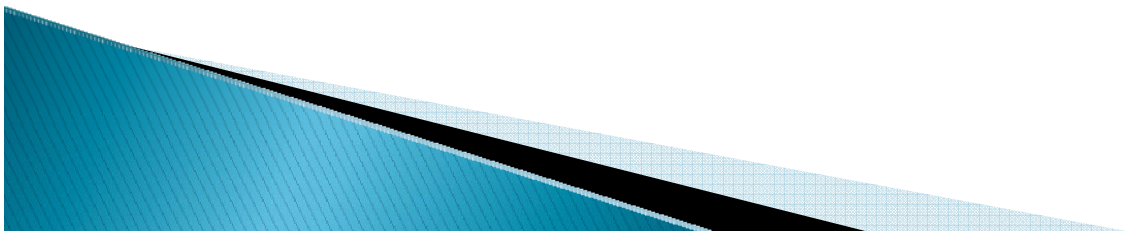
# Process Variations

- ▶ Chip manufacturing involves complex chemical and physical processes.
- ▶ Tighter pitches and bounds make process variations unavoidable.
- ▶ Types of process variations –
  1. Systematic process variations – layout dependent
  2. Random process variations –
    - a. Inter-die Random variations – depend on circuit design
    - b. Intra-die Random variations – dominant components
      - (1) Independent random variations
      - (2) Partially correlated random variations
  3. Overall intra-die variations at  $n$  locations –

$$p(n) = \mu(n) + \varepsilon(n)$$

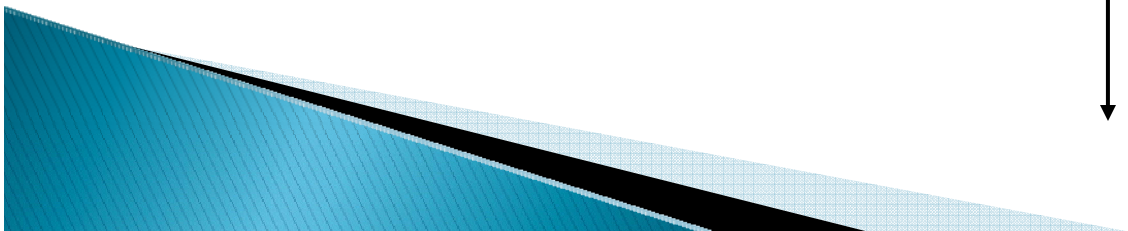
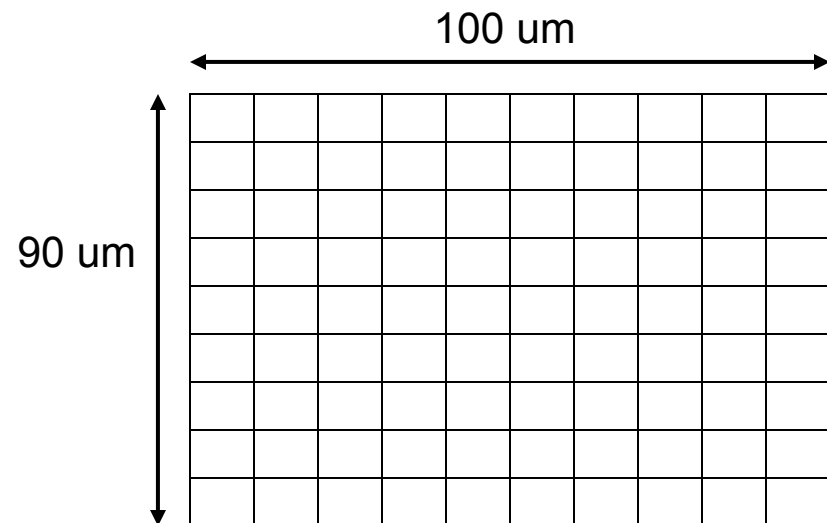
where  $\mu(n)$  – systematic intra-die variations

$\varepsilon(n)$  – random intra-die variations



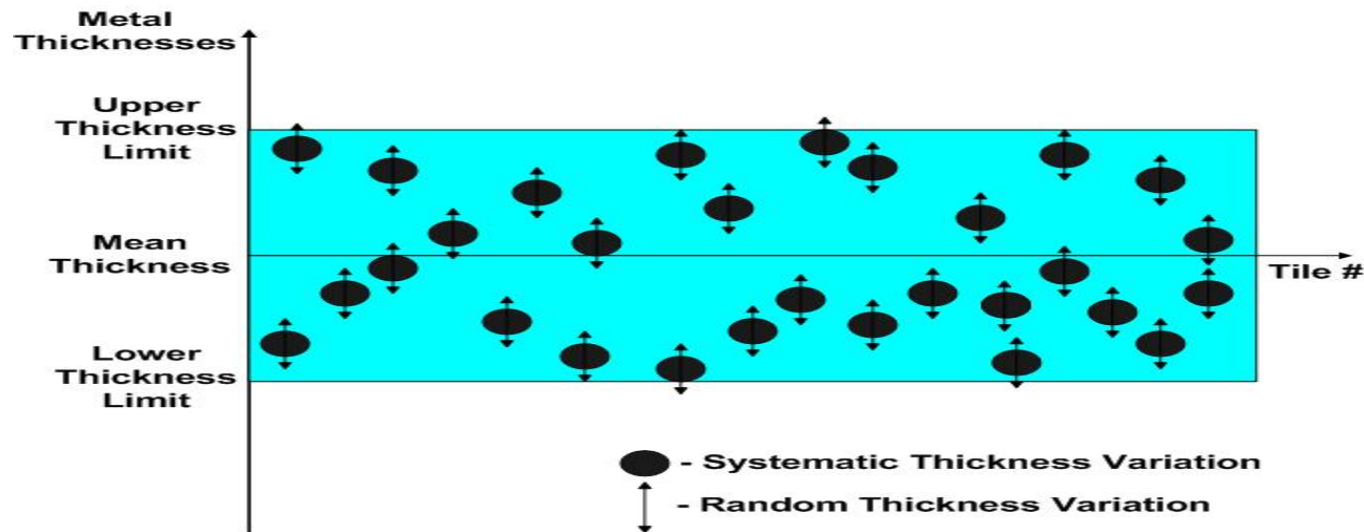
# CMP Yield

- ▶ Chemical Mechanical Planarization (CMP) – used in patterning Cu interconnects.
- ▶ CMP model – Yield is probability of thicknesses at all locations lying within the Upper and Lower thickness limits.
- ▶ For simplicity, a chip is meshed into a no. of tiles.
- ▶ Each tile is a location monitored for interconnect thickness.
- ▶ Meshing a chip into small tiles –
  - Dimension –  $100\ \mu\text{m} \times 90\ \mu\text{m}$ .
  - Size of each tile –  $10\ \mu\text{m} \times 10\ \mu\text{m}$
  - Total no. of tiles – 90
  - No. of locations monitored – 90

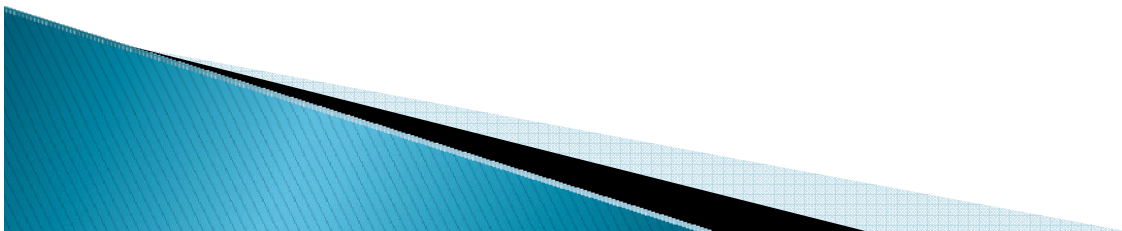


# Illustrating a CMP Model

- ▶ Process variations in interconnect thicknesses at  $n$  locations –



- ▶ CMP Yield –Probability for thickness at  $n$  locations to lie in the shaded region.

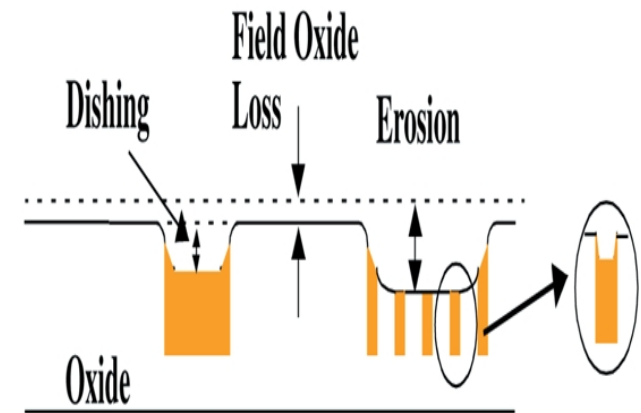


# Need for Predicting CMP Yield

- ▶ Factors making Yield Prediction important –

1. Presence of Process Variations
2. Shrinking feature sizes

- ▶ Dishing – Excessive polishing of Cu.
- ▶ Erosion – Loss in field oxide between interconnects.
- ▶ Potential open and short faults in interconnects.
- ▶ Predict Yield in circuit design stages to get Yield friendly design.



# Equations for Yield Prediction

- Yield is obtained via numerical integration of a joint PDF -

$$Y = \int_L^U \int_L^U \dots \int_L^U \phi(p) \cdot dp_1 dp_2 \dots dp_n \quad \dots(1)$$

$$\phi(p) = \frac{(\vec{p} - \vec{\mu})^T \Sigma^{-1} (\vec{p} - \vec{\mu})}{\sqrt{(2\pi)^n |\Sigma|}} \quad \dots(2)$$

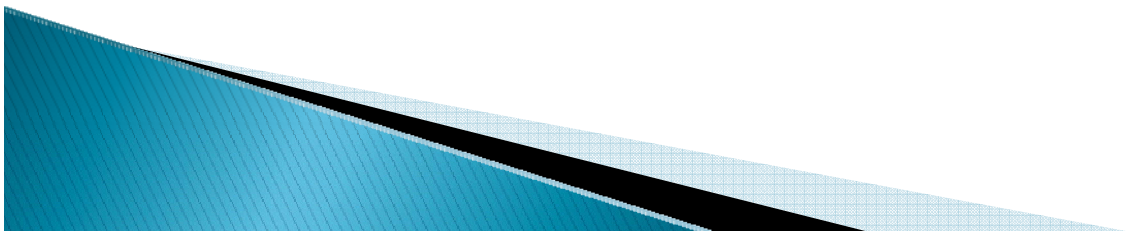
Where  $\Sigma$  - covariance matrix for the  $n$  variables –  $\{p_1, p_2, \dots, p_n\}$   
 $U, L$  &  $\mu$  - upper and lower thickness limits, & mean thickness value.

Yield equation (1) can be decomposed as –

$$Yield = Y_U + Y_L - 1 \quad \dots(3)$$

Where  $Y_U$  (*High Yield*) - probability for thickness at all locations to stay below upper thickness limit.

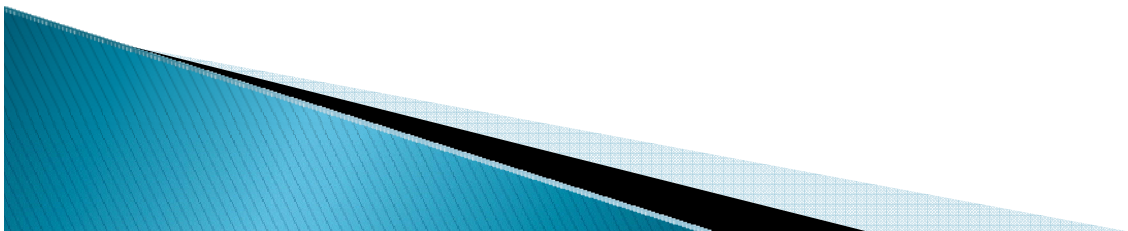
$Y_L$  (*or Low Yield*) - probability for thickness at all locations to stay above lower thickness limit.





# Presentation Outline

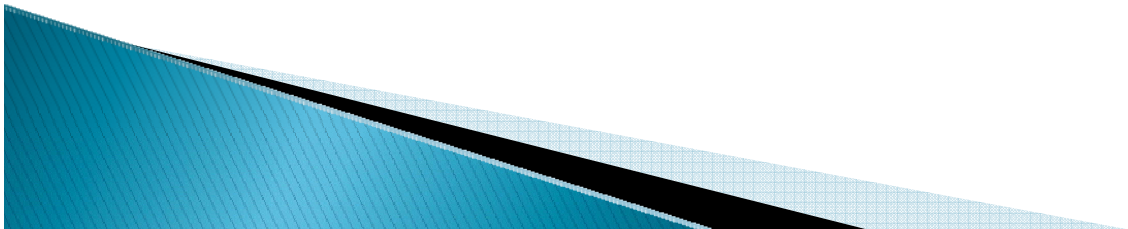
- ✓ What is Yield?
- **Difficulties in Yield Prediction**
- Previous Research
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# Difficulties in Yield Prediction

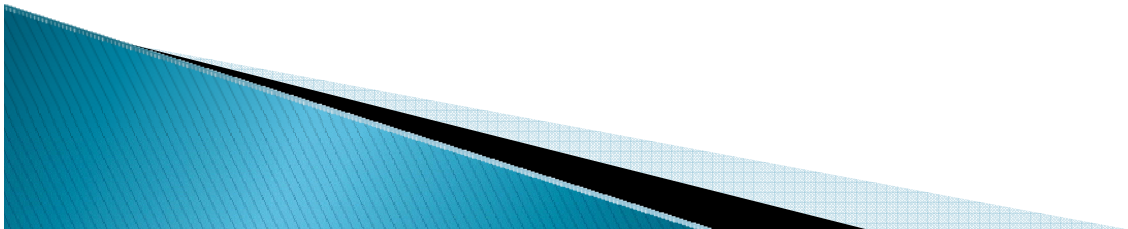
## ► Issues Affecting Yield Prediction –

1. Large number of locations to monitor ( $10^4$ – $10^6$ ).
2. Independent & partial correlations between locations.
3. Large memory requirements.
4. Complexity of numerical integration due to problem size.



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# Previous Research

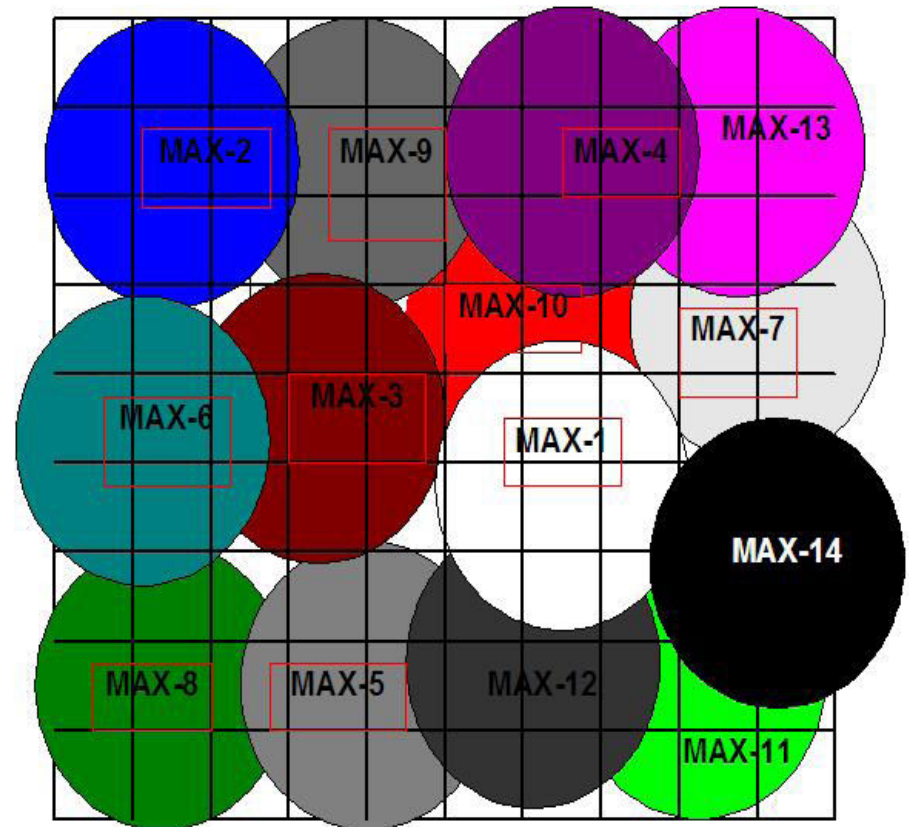
- ▶ Perfect Correlation Circles (PCC) approach – to reduce no. of tiles.
- ▶ Luo, et al., DAC 2006

## Algorithm for PCC Approach

1. Find tile with maximum thickness  $MAX_1$ .
2. Form  $PCC - CIRCLE_1$  (centre at  $MAX_1$ , pre-fixed radius).
3. Find tile with maximum thickness  $MAX_2$  outside  $CIRCLE_1$ .
4. Form  $PCC CIRCLE_2$  (centre at  $MAX_2$ ).
5. Form similar  $PCCs$  until no tiles are left uncovered by  $PCCs$ .
6. Centers of  $PCCs$  ( $MAX_1, \dots, MAX_m$ ) form reduced set of variables.
7. Use Genz algorithm to compute yield.

# Example Showing Reduction

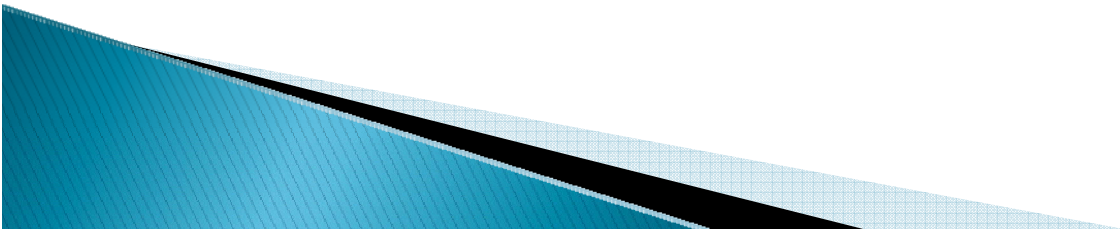
- ▶ Let the setup look like this after reduction →
- ▶ Reduction from 90 tiles to 14 variables (the centres of PCCs –  $MAX_1, \dots, MAX_{14}$ .)
- ▶ PCCs are formed in a sequence –  
 $MAX_1 - CIRCLE_1,$   
 $MAX_2 - CIRCLE_2,$   
.....,  
 $MAX_{13} - CIRCLE_{13},$   
 $MAX_{14} - CIRCLE_{14}.$



- ▶ Compute Low Yield using similar procedure.

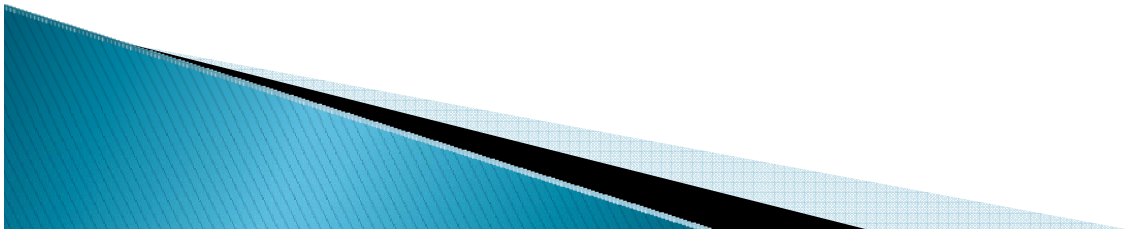
# Pros and Cons of the PCC Approach

- ▶ Advantages –
  1. Reduction in problem complexity.
  2. Reduced run-time.
  
- ▶ Disadvantages –
  1. Yield Accuracy is affected.
    - a. Large PCC radius → Heavy reduction in variables.  
(over-estimation in yield)
  
    - b. Small PCC radius → Lesser reduction in Variables.  
→ more accurate yield estimate  
(but larger run-time)



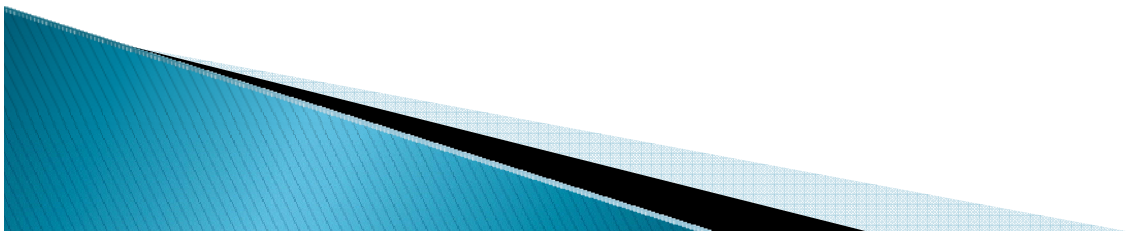
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# Proposed Research

- ▶ Develop reduction methods to –
  1. Reduce problem complexity.
  2. Reduce effect on yield accuracy.
- ▶ Two new methods for predicting yield –
  1. *Orthogonal Principal Component Analysis (OPCA)*
  2. *Hierarchical Adaptive Quadrisection (HAQ)*





# Yield Model used in this Work

- ▶ Let vector  $\vec{p}$  be metal thicknesses at  $n$  locations –  
$$\vec{p} = (p_1, p_2, \dots, p_n)^T$$

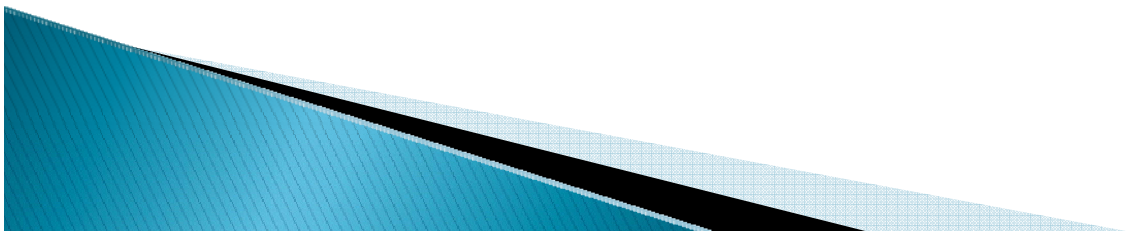
- ▶ This vector can be decomposed as follows –

$$p_i = \mu_i + \delta_i \quad \text{and} \quad \mu_i = \mu + \Delta_i$$

where  $\mu$  – nominal value

$\Delta_i$  – systematic variation

$\delta_i$  – random variation



# Orthogonal Principal Component Analysis

- ▶ Objective – Transform correlated random variables to a reduced & uncorrelated set through an orthogonal base
- ▶ Procedure –
  1. Form initial thickness vector, correlation & covariance matrices.
  2. Perform Eigenvalue Decomposition.
  3. Transform into to set of uncorrelated variables through a mapping matrix.
  4. Discern unwanted eigenvalues to get reduced set of uncorrelated variables.

- ▶ Initial Setup for OPCA –

Let the initial thickness variations at  $n$  locations be –

$$\vec{\delta} = \{\delta_1, \delta_2, \dots, \delta_n\}^T \quad \dots(1)$$

- ▶ Let  $\Gamma_{n \times n}$  and  $\Sigma_{n \times n}$  be the corresponding correlation and covariance matrices.  
Let  $\sigma_i^2$  be the variance.

$$\Gamma(\vec{\delta}) = (\Gamma_{ij})_{n \times n} \quad \text{and} \quad \Sigma(\vec{\delta}) = \Gamma(\vec{\delta})_{n \times n} \cdot \sigma_i \cdot \sigma_j \quad \dots(2)$$

# Using Eigenvalue Decomposition

- ▶ Re-express covariance matrix using Eigenvalue Decomposition -

$$\Sigma(\vec{\delta}) = Q \cdot \Lambda(\vec{\delta}) \cdot Q^T \quad \dots(3)$$

where  $\Lambda(\vec{\delta})$  - eigenvalue (diagonal) matrix

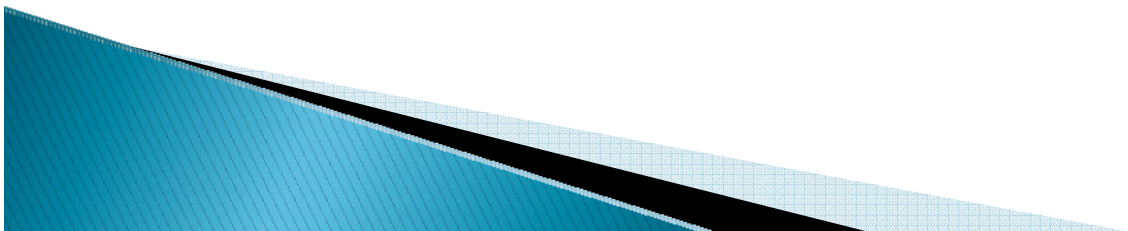
$Q$  - corresponding eigenvector matrix

- ▶ The diagonal matrix  $\Lambda(\vec{\delta})_{n \times n}$  will look like -

$$\Lambda(\vec{\delta}) = \begin{pmatrix} \lambda_1 & 0 & \dots & \dots & 0 \\ 0 & \lambda_2 & \dots & \dots & 0 \\ 0 & 0 & \dots & \dots & 0 \\ 0 & 0 & \dots & \dots & 0 \\ 0 & 0 & \dots & \dots & 0 \\ 0 & 0 & \dots & \dots & \lambda_n \end{pmatrix} \quad \dots(4)$$

such that  $\lambda_1 \geq \lambda_2 \geq \dots \geq \lambda_n$

- ▶ Eigenvalue decomposition gives dominant directions in covariance relationship between a correlated set of variables.



# Mapping into a New Set of Variables

- ▶ Let  $\mathcal{E}_{n \times 1}$  be the new set of uncorrelated variables such that -

$$\vec{\delta} = B \cdot \vec{\varepsilon} \quad \dots(5)$$

- ▶ Without loss of generality, assume B follows a Gaussian Distribution -

$$\mu(\vec{\varepsilon}) = 0 \quad \& \quad \Lambda(\vec{\varepsilon}) = I \quad \dots(6)$$

- ▶ The matrices  $\mathcal{D}_{n \times 1}$  and  $\mathcal{E}_{n \times 1}$  are related as follows -

$$\Lambda(\vec{\delta}) = J \cdot \Lambda(\vec{\varepsilon}) \cdot J^T \quad \dots(7)$$

where

$$J = \begin{pmatrix} \sqrt{\lambda_1} & 0 & \dots & 0 \\ 0 & \sqrt{\lambda_2} & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & \sqrt{\lambda_n} \end{pmatrix}$$

- ▶ Transforming through an Orthogonal Base - Let B be the mapping matrix -

$$B = Q \cdot J \quad \dots(8)$$

# Transforming through an Orthogonal Base .... Contd..

- ▶ Correspondingly, we have -

$$\vec{\delta} = B \cdot \varepsilon = Q \cdot J \cdot \vec{\varepsilon} \quad \dots(9)$$

- ▶ This transforms the initial set of correlated random variables to an uncorrelated set through an orthogonal base.

$$\Sigma(\vec{\delta}) = Q \cdot \Lambda(\vec{\delta}) \cdot Q^T = Q \cdot J \cdot \Lambda(\vec{\varepsilon}) \cdot (Q \cdot J)^T \quad \dots(10)$$

- ▶ Reducing the no. of uncorrelated variables -

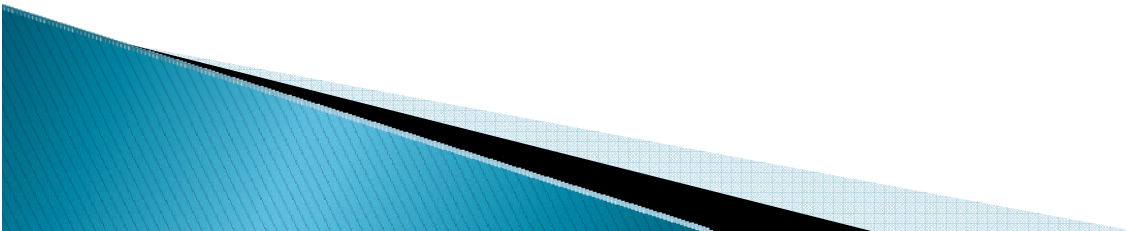
1. After reduction, if we have  $k$  variables, then matrices  $\Lambda(\vec{\delta})$  and  $J_{k \times k}$  are -

$$\Lambda(\vec{\delta}) = \begin{pmatrix} \lambda_1 & 0 & \dots & 0 \\ 0 & \lambda_2 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & \lambda_k \end{pmatrix} \quad \& \quad J = \begin{pmatrix} \sqrt{\lambda_1} & 0 & \dots & 0 \\ 0 & \sqrt{\lambda_2} & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & 0 \\ 0 & 0 & \dots & \sqrt{\lambda_k} \end{pmatrix} \quad \dots(11)$$

2. The corresponding sizes of matrices  $B$  and  $Q$  become  $n \times k$ , thus giving reduction.

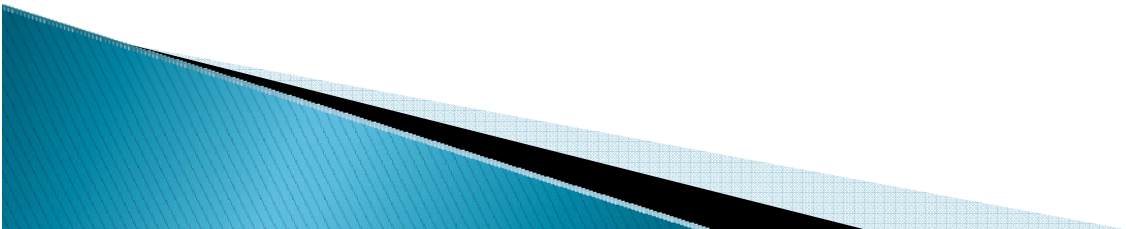
# Hierarchical Adaptive Quadrisection

- ▶ Conquer and divide based clustering approach.
- ▶ Clustering done using *sub-regions* (similar to PCCs).
- ▶ Clustering in *sub-regions* is based on thickness variations.
- ▶ Sizes of clusters are not homogeneous.



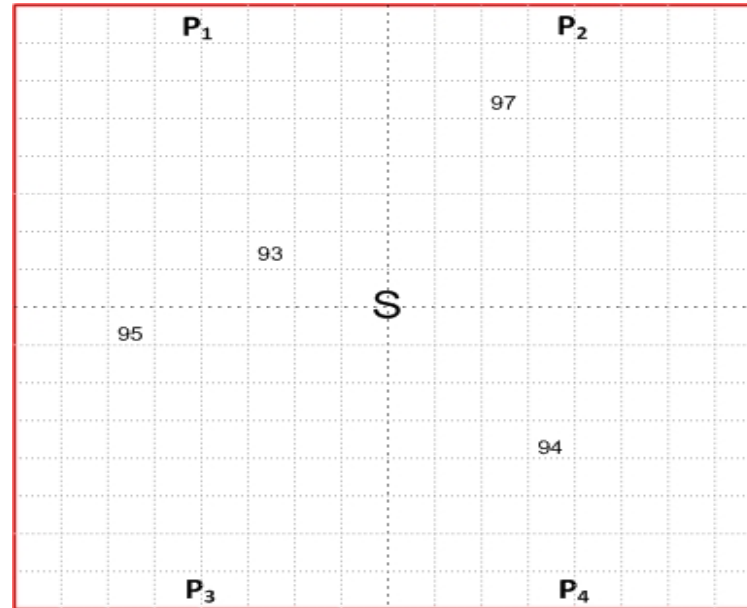
# Computing High Yield using HAQ

- ▶ Consider entire chip as one basic *sub-region S*.
- ▶ Sub-region *S* consists of tiles used in evaluating yield.
- ▶ Threshold thickness value  $\theta$  decides possibility of clustering.
- ▶ Threshold  $\theta$  tells on variations in thickness of tiles in a sub-region.



# Working Model for Computing High Yield

- ▶ Stage 1:– Sub-region S covers the entire chip. Let  $\theta$  be 10.

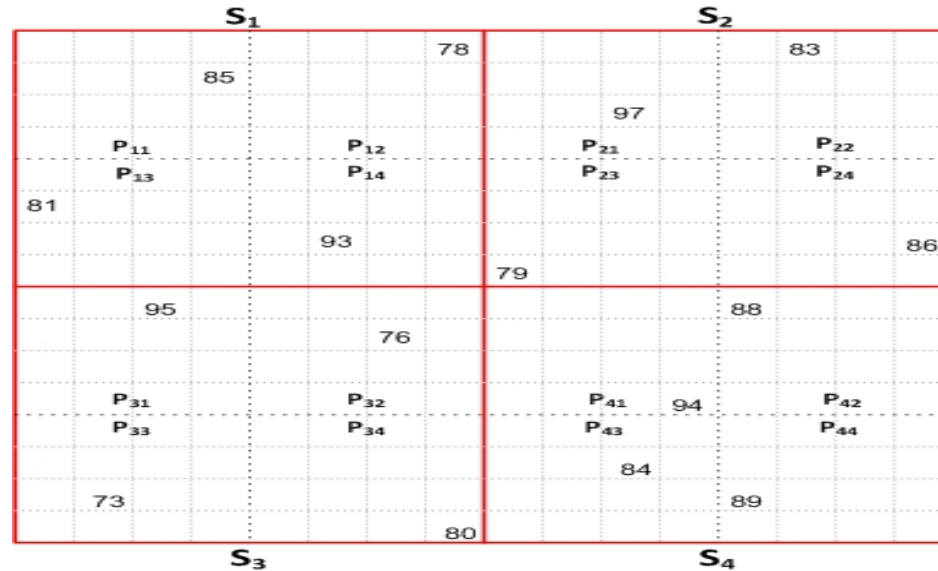


Sub-region Monitored	Max Thickness		$C_d$	$C_d \leq \theta$	Next Action
	Critical	Non-Critical			
S	97	93, 95, 94	2	Yes	<i>Quadrisect</i>



# Working model for High Yield ..... Stage 2

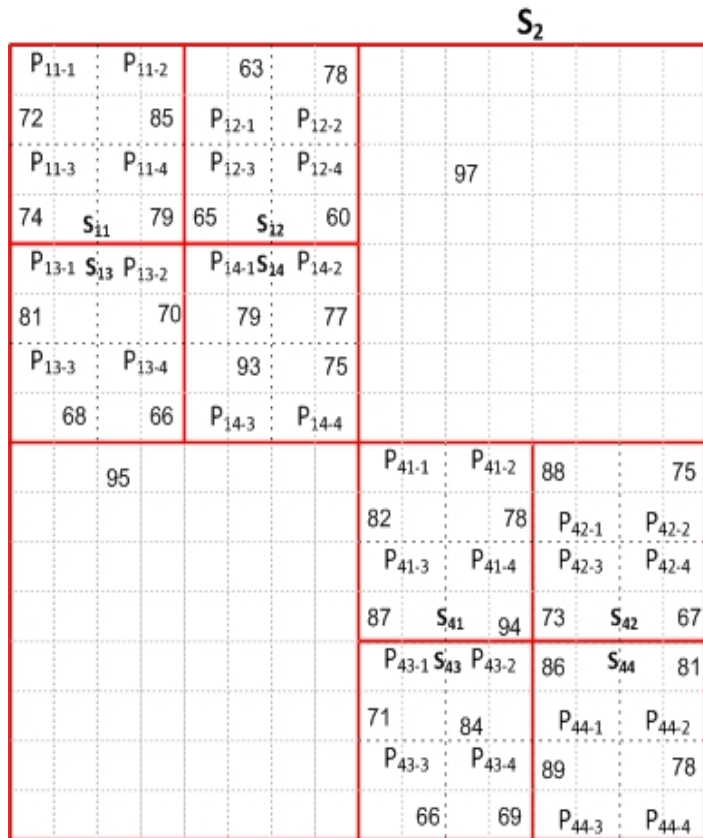
- ▶ Stage 2 – After forming sub-regions  $S_1$ ,  $S_2$ ,  $S_3$  and  $S_4$ .



Sub-region Monitored	Max Thickness		$C_d$	$C_d \leq \theta$	Next Action
	Critical	Non-Critical			
$S_1$	93	85, 78, 81	8	Yes	<i>Quadrisect</i>
$S_2$	97	83, 79, 86	11	No	<i>Retain</i>
$S_3$	95	76, 73, 80	15	No	<i>Retain</i>
$S_4$	94	88, 84, 89	5	Yes	<i>Quadrisect</i>

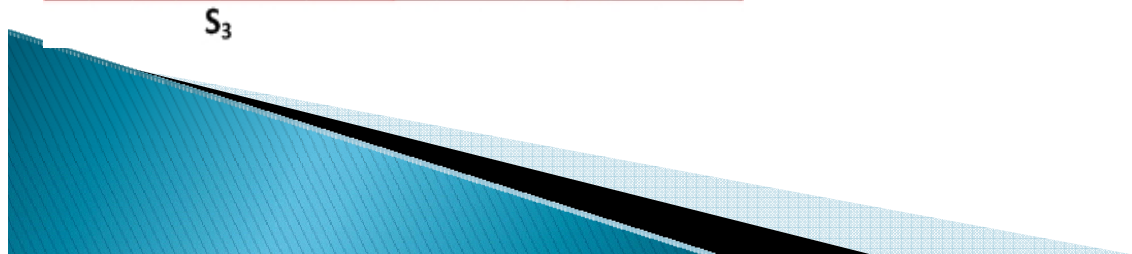
# Working Model for High Yield .... Stage 3

- Stage 3 – Inside sub-regions  $\{S_{11}, S_{12}, S_{13}, S_{14}\}$  &  $\{S_{41}, S_{42}, S_{43}, S_{44}\}$ .



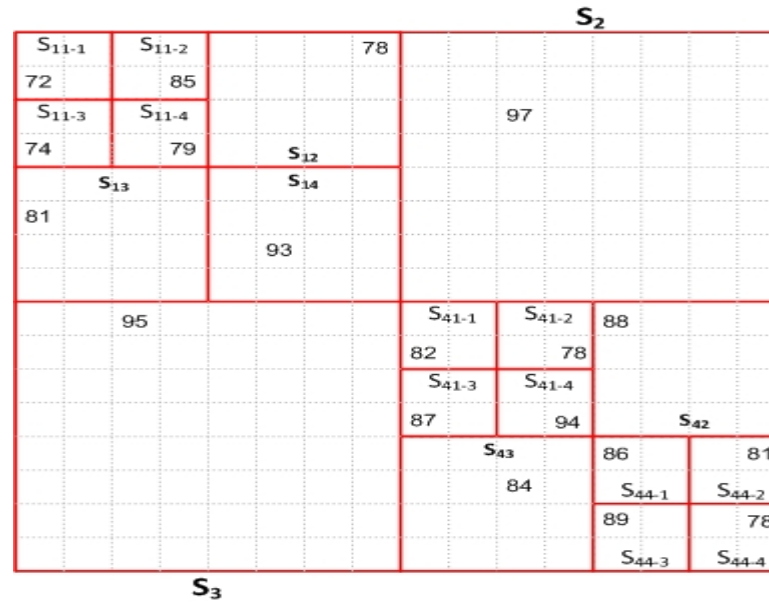
Sub-region Monitored	Max Thickness		$C_d$	$C_d \leq \theta$	Next Action
	Critical	Non-Critical			
$S_{11}$	85	72, 74, 79	6	Yes	<i>Quadrisect</i>
$S_{12}$	78	63, 65, 60	13	No	<i>Retain</i>
$S_{13}$	81	70, 68, 66	11	No	<i>Retain</i>
$S_{14}$	93	79, 77, 75	16	No	<i>Retain</i>

Sub-region Monitored	Max Thickness		$C_d$	$C_d \leq \theta$	Next Action
	Critical	Non-Critical			
$S_{41}$	94	82, 78, 87	7	Yes	<i>Quadrisect</i>
$S_{42}$	88	75, 73, 67	13	No	<i>Retain</i>
$S_{43}$	84	71, 66, 69	11	No	<i>Retain</i>
$S_{44}$	89	86, 81, 78	3	Yes	<i>Quadrisect</i>

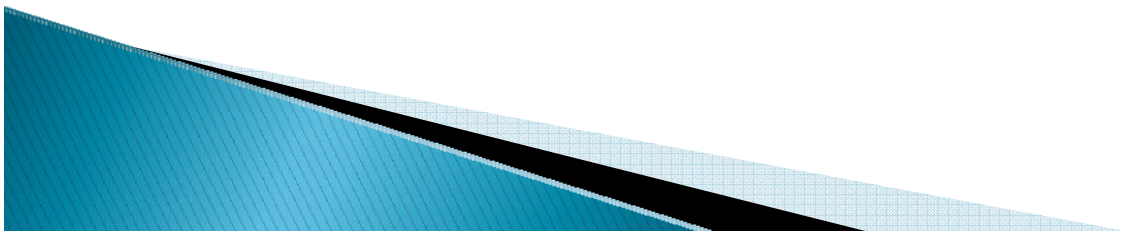


# Working Model for High Yield ... After Stage 3

- After Stage 3 in the HAQ algorithm, the setup will look like -



- Stage 3, the chip is covered by *19 basic sub-regions*.
- Further clustering based on thickness variations in new sub-regions.



# Computing Low Yield using HAQ

- ▶ Clustering based on minimum thickness variations in sub-regions.

## Comparing HAQ and PCC approaches

### HAQ Approach

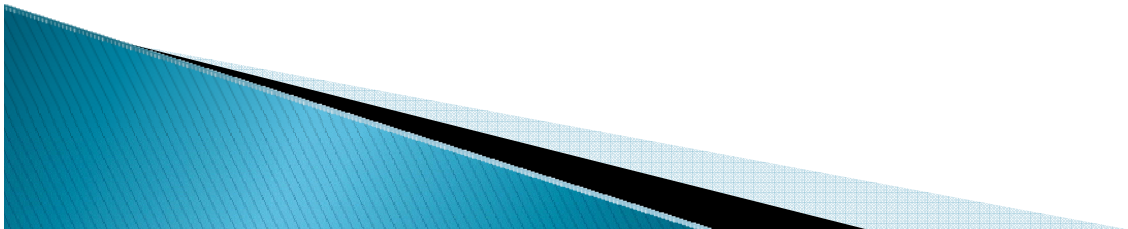
- ▶ Heterogeneous cluster sizes
- ▶ Clustering based on variations and sensitivity inside sub-regions
- ▶ No. of Clusters in working model –
  - Stage-1 → 4
  - Stage-2 → 10
  - Stage-3 → 19

### PCC Approach

- ▶ Homogeneous cluster sizes
- ▶ No importance for sensitivity in variations for clustering
- ▶ No. of Clusters in each stage of the working model
  - Stage-1 → 4
  - Stage-2 → 16
  - Stage-3 → 64

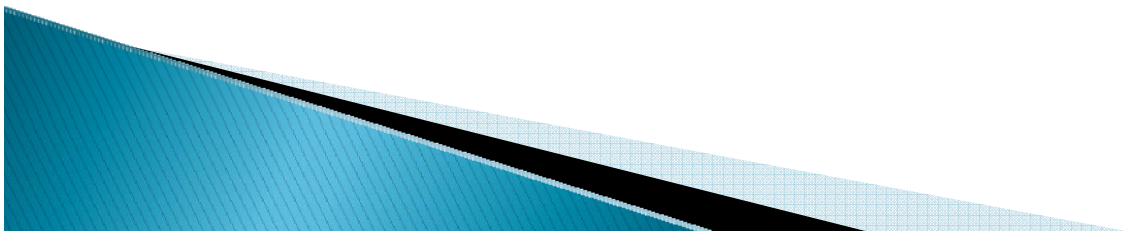
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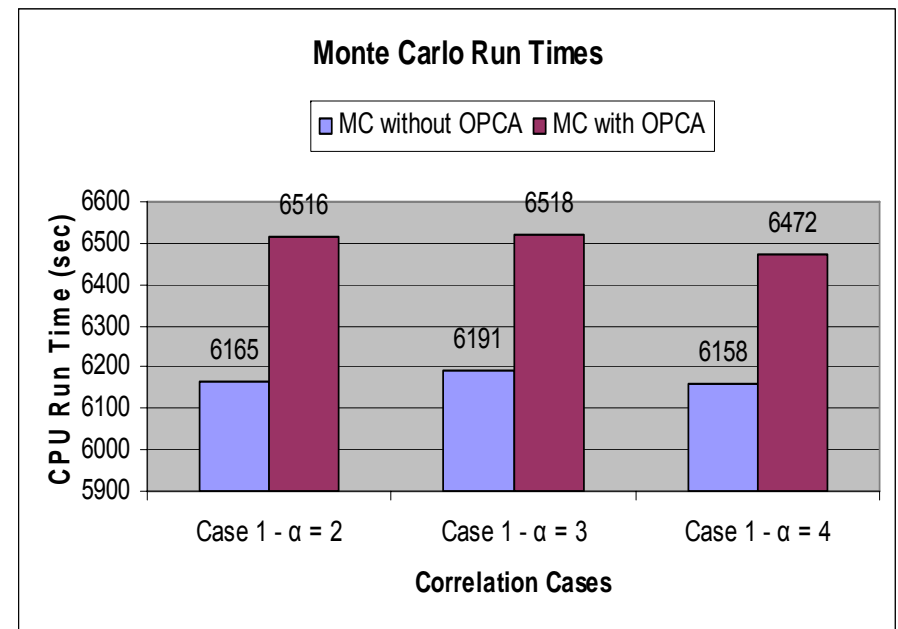
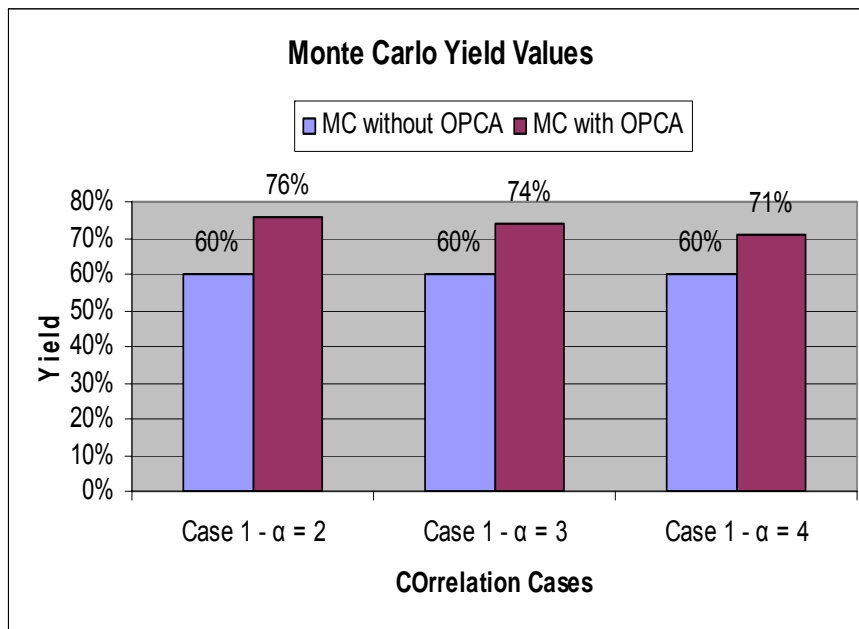
# Simulation Results

- ▶ Experiments simulated –
  1. Monte Carlo (MC) Simulations
  2. PCC method
  3. OPCA method
  4. HAQ method
- ▶ Yield evaluated for three cases of correlation –  $(-\alpha \times 10^{-5} x) + 0.9958$   
where  $\alpha = \{2, 3, 4\}$  and  $x$ – distance between centres of different tiles.
- ▶ Simulation Inputs –
  1. Input thickness –
    - Mean thickness value – 0.3580  $\mu\text{m}$
    - Upper thickness limit – 0.4580  $\mu\text{m}$
    - Lower thickness limit – 0.2580  $\mu\text{m}$
    - Standard deviation – 0.02  $\mu\text{m}$

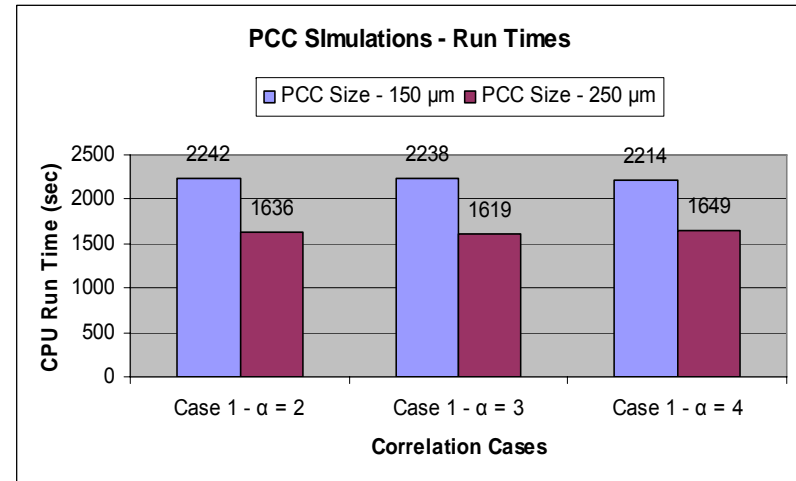
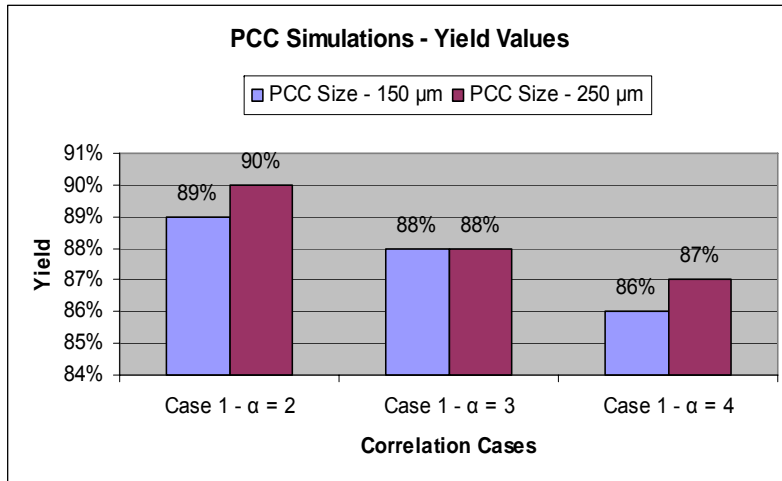


# Monte Carlo Simulations

- ▶ Correlation Equation:  $-3 \times 10^{-5} x + 0.9958$
- ▶ Initial seed = 5



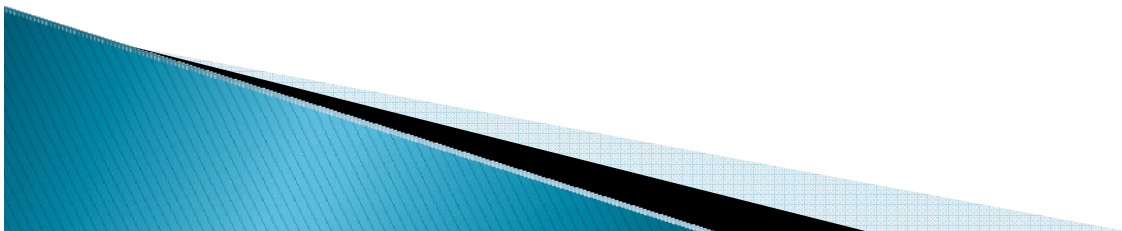
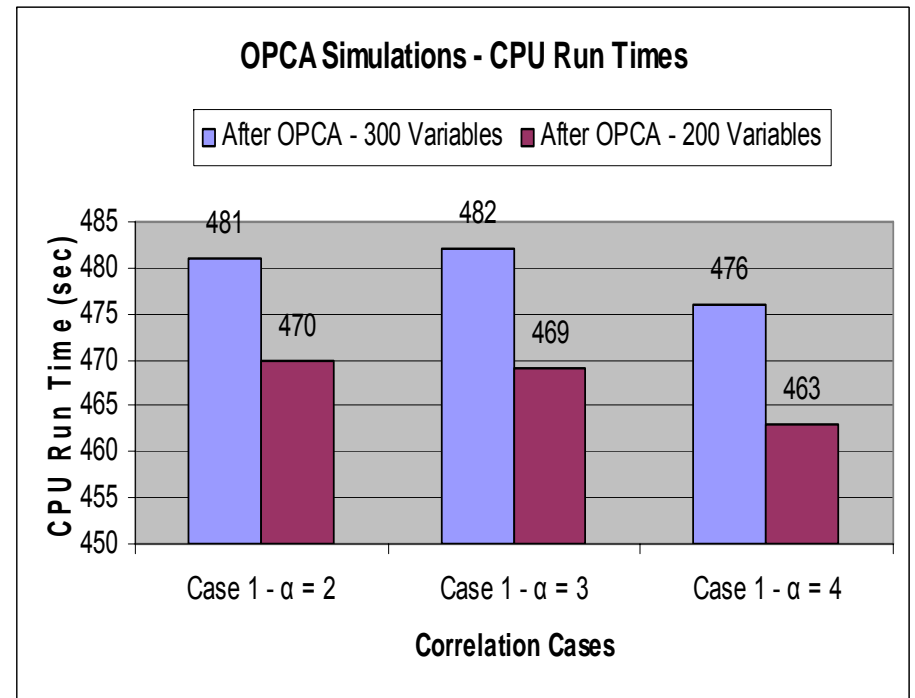
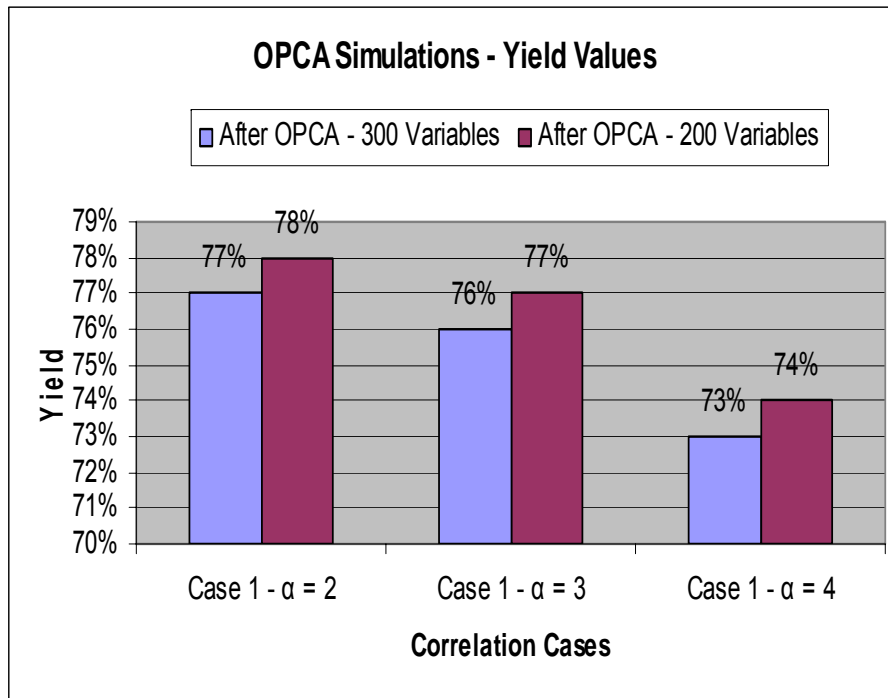
# PCC Simulations



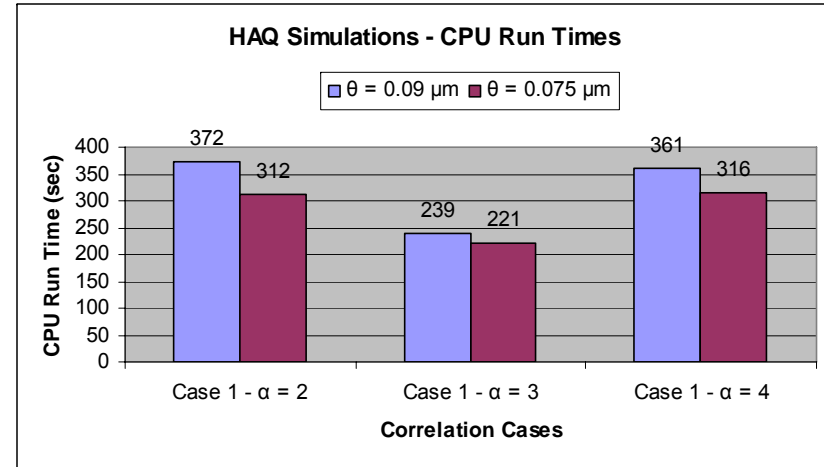
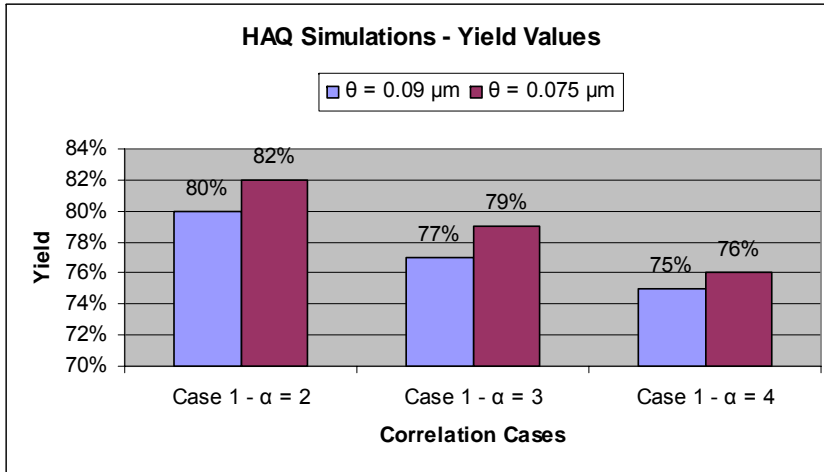
Correlation Equation	PCC Size	No. of Variables
$- 2 \times 10^{-5} x + 0.9958$	150 $\mu\text{m}$	431 / 435
	250 $\mu\text{m}$	305 / 310
$- 3 \times 10^{-5} x + 0.9958$	150 $\mu\text{m}$	432 / 427
	250 $\mu\text{m}$	305 / 310
$- 4 \times 10^{-5} x + 0.9958$	150 $\mu\text{m}$	429 / 425
	250 $\mu\text{m}$	307 / 308



# OPCA Simulations



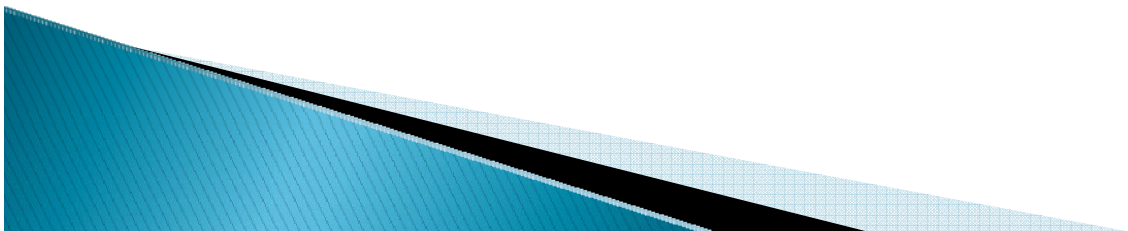
# HAQ Simulations



Correlation Equation	$\theta$	No. of Variables
$- 2 \times 10^{-5} x + 0.9958$	0.09 $\mu\text{m}$	175/178
	0.075 $\mu\text{m}$	153/155
$- 3 \times 10^{-5} x + 0.9958$	0.09 $\mu\text{m}$	80/79
	0.075 $\mu\text{m}$	61/61
$- 4 \times 10^{-5} x + 0.9958$	0.09 $\mu\text{m}$	172/170
	0.075 $\mu\text{m}$	148/143

# Observations in Results

- ▶ Monte Carlo without OPCA –  
Neglecting correlation under-estimates yield.
- ▶ OPCA –  
Less variable reduction → better accuracy, yield is closer to Monte Carlo.
- ▶ PCC –  
Larger PCC sizes → more reduction → over-estimated yield value  
Smaller PCC sizes → improves accuracy in yield → longer run time
- ▶ HAQ –  
Higher threshold values → less reduction (fine-grained grid)  
→ improved accuracy  
Smaller threshold values → over-estimated yield



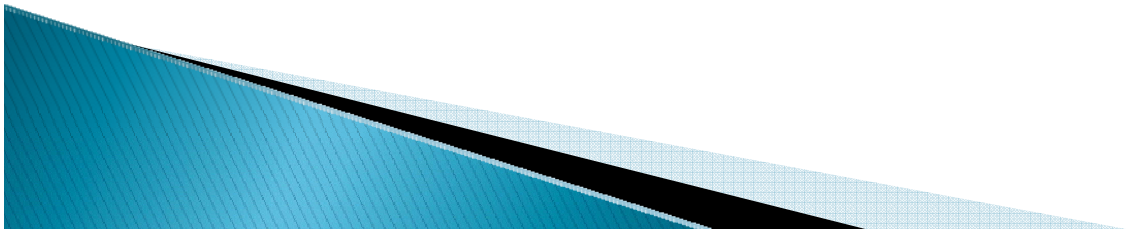
# Comparisons in Results

- ▶ Comparing yield accuracy and algorithm run time –

Correlation Equation	Method	Yield Error	Speedup
$-3 \times 10^{-5}x + 0.9958$	PCC	18.9%	1x
	OPCA	2.7%	4.6x
	HAQ	4.1%	9.4x
$-4 \times 10^{-5}x + 0.9958$	PCC	21.1%	1x
	OPCA	2.8%	4.7x
	HAQ	5.6%	6.2x
$-2 \times 10^{-5}x + 0.9958$	PCC	17.1%	1x
	OPCA	1.3%	4.7x
	HAQ	5.3%	6x

# Presentation Outline

- ✓ What is Yield?
- ✓ Difficulties in Yield Prediction
- ✓ Previous Research
- ✓ Proposed Research
- ✓ Simulation Results
- **Conclusion**

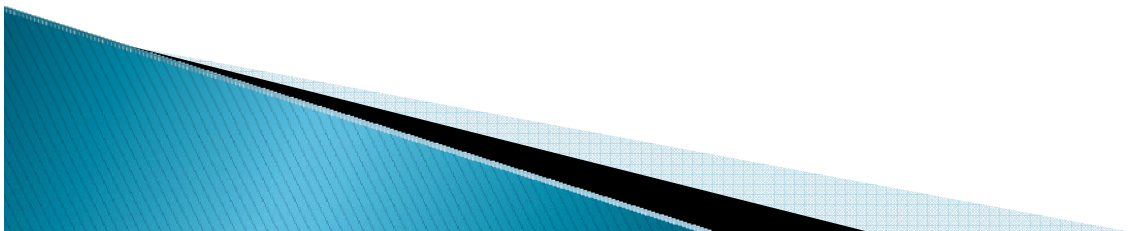


# Conclusion

- ▶ Yield prediction is complex –
  1. Large number of locations monitored
  2. Partial & independent correlations between locations
- ▶ New methods used in yield prediction –
  1. Orthogonal Principal Component Analysis
  2. Hierarchical Adaptive Quadrisection
- ▶ Both reduce complexity & have less impact on Yield Accuracy.

## Scope for Future Work

Extend same methods to predict timing yield in sequential circuits.



**Thank You**

